ABGOGIATION CONNECTING ELECTRONICS (MOUSTRIES*) international and Pan-American co	urn. Illinois. All rights reserved u	nder both This doc level par	ument is a declara ts, the declaration	tion of the substand encompasses all lo	es within the manufactur wer level materials for wl	er listed item. Note: hich the manufacture	if the item is an a er has engineering	ssembly with lower responsibility.	
IPC Web Site for Information on I   http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					
Supplier Information									
apany name* Company unique ID			Unique ID Authority			Response Date*			
onsemi						2025-06-09			
Contact Name	Title - Contact		Phone - Contact*			Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com			
thorized Representative* Title - Representative			Phone - Representative*			Email - Representative*			
Product-Env-Stewards Product Enviro Comp		Compliance N		NA			Product-Env-Stewards@onsemi.com		
Requester Item Number Mfr Item	n Number Mfr Item Name		Effective Dat	e Version	Manufacturing Site	Weight*	UOM	Unit Type	
NCP1240 R2G	00CAHAB0D Fixed Frequency of for Flyback Conve	Current Mode Controller erters	2025-06-09		CNW	71.87	mg	Each	
Manufacturing Proccess Information									
Terminal Plating / Grid Array Material T	ial Terminal Base Alloy J-STD-0		Peak Pro	Peak Process Body Temperature Max Time at Pea		Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy 1		1	260	С	30	seconds 3			
Comments									
evel 1 - maximum time at peak temperature during sol	dering is 10-30 seconds								
For more information regarding material composition	0								

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

select a RoHS exemption, if applied	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
sigma range of distribution unless	,	TT '4 . 63.5	<b>.</b>	S 1 4	C L C	E (		TT 14 63.6
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.48	mg	Supplier	Silver (Ag)	7440-22-4		0.7871	mg
			Supplier	Zinc (Zn)	7440-66-6		0.075	mg
			Supplier	Iron (Fe)	7439-89-6		0.937	mg
			Supplier	Copper (Cu)	7440-50-8		35.681	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg